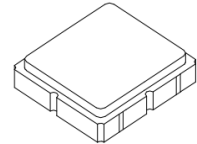


SF2321D

**1090 MHz
SAW Filter**



SM3838-6

- **Low-loss SAW Filter**
- **No Matching Required for 50 ohm Source/Load**
- **3.8 x 3.8 x 1.4 mm Surface-mount Package**
- **Complies with Directive 2002/95/EC (RoHS)**
- **Moisture Sensitivity Level: 1**

Absolute Maximum Ratings

Rating	Value	Units
Maximum Incident Power in Passband	+20	dBm
Maximum DC Voltage on any Non-ground Terminals	3	VDC
Operating Temperature Range	-40 to +85	°C
Storage Temperature Range in Tape and Reel	-55 to +85	°C
Suitable for Lead-free Soldering - Maximum Soldering Profile	260°C for 30 s	

Electrical Characteristics

Characteristic	Sym	Notes	Min	Typ	Max	Units
Center Frequency	f _C			1090		MHz
Insertion Loss, 1075 to 1105 MHz	IL			2.4	3.0	dB
Amplitude Ripple, 1085 to 1095 MHz				0.1	1.0	dB _{P-P}
VSWR, 1075 to 1105 MHz				1.8:1	2.1:1	
Rejection Referenced to 0 dB:						dB
DC to 970 MHz			25	30		
1150 to 1300 MHz			25	33.5		
Single-ended Source Impedance	50 ohm					
Single-ended Load Impedance	50 ohm					

Case Style	SM3838-6 3.8 x 3.8 mm Nominal Footprint					
Lid Symbolization (Y=year, WW=week, S=shift) dot=pin 1 indicator	A81, YWWS					
Standard Reel Quantity	Reel Size 7 Inch	500 Pieces/Reel				
	Reel Size 13 Inch	3000 Pieces/Reel				

Electrical Connections

Connection	Terminals
Port 1	2
Port 2	5
Case Ground	All others

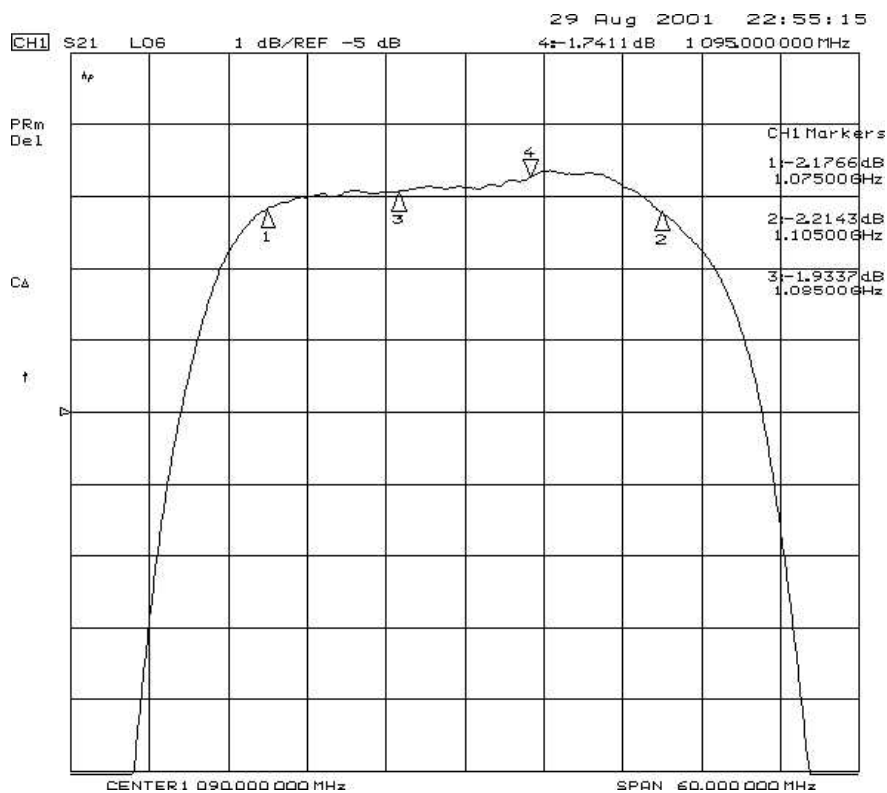
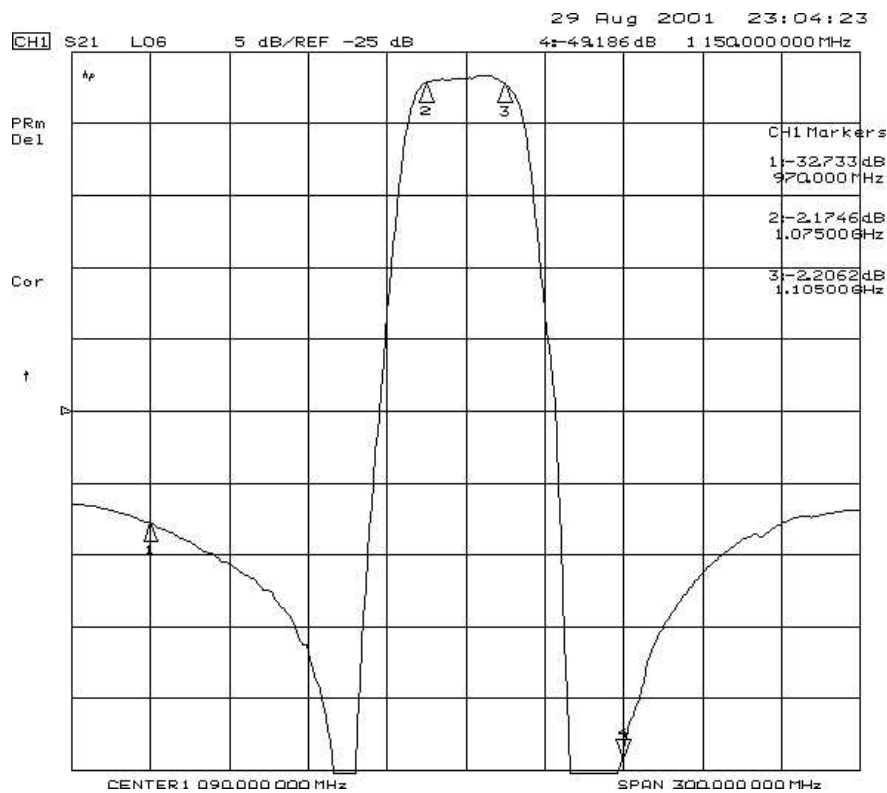


CAUTION: Electrostatic Sensitive Device. Observe precautions for handling.

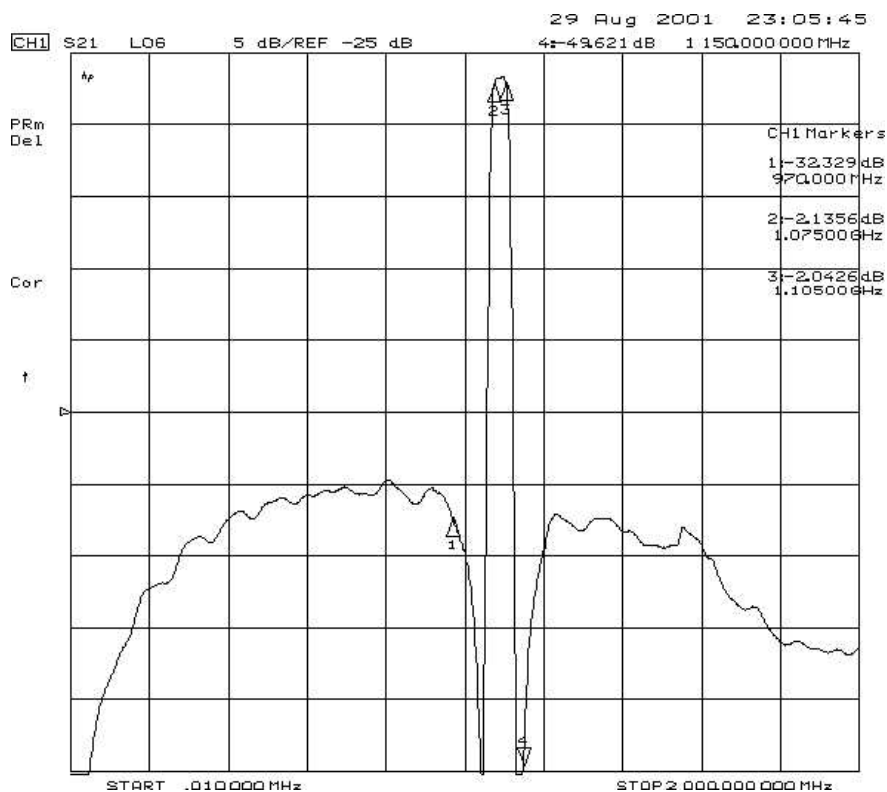
NOTES:

1. The design, manufacturing process, and specifications of this device are subject to change.
2. US or International patents may apply.
3. RoHS compliant from the first date of manufacture.

Frequency Characteristics

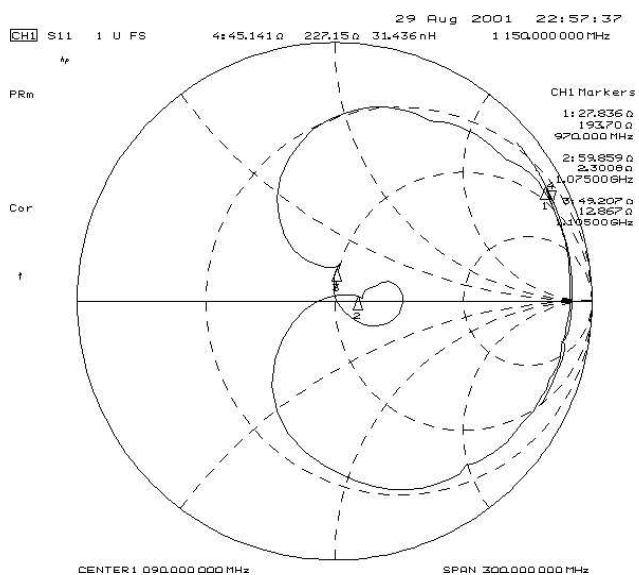


Wideband

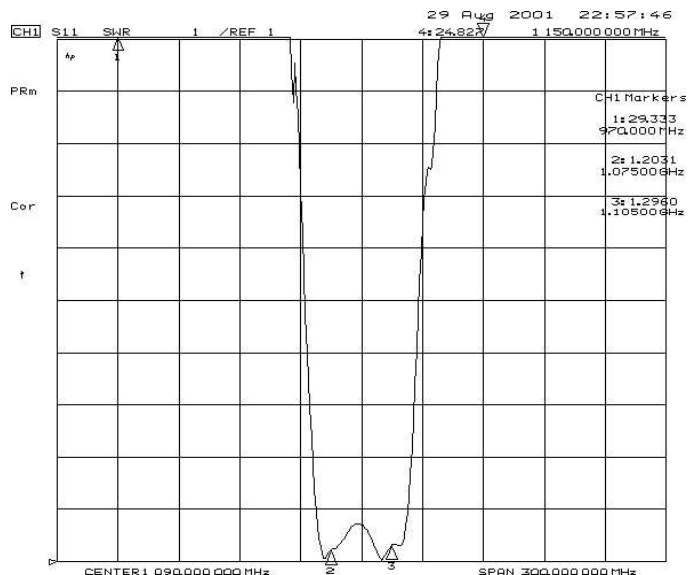


Reflections Functions:

Smith Chart



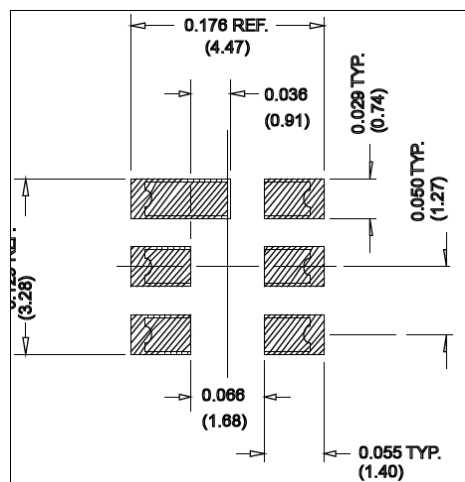
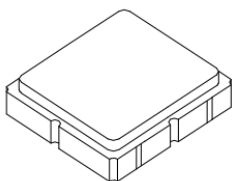
VSWR



SM3838-6 Case

6-Terminal Ceramic Surface-Mount Case

3.8 X 3.8 mm Nominal Footprint



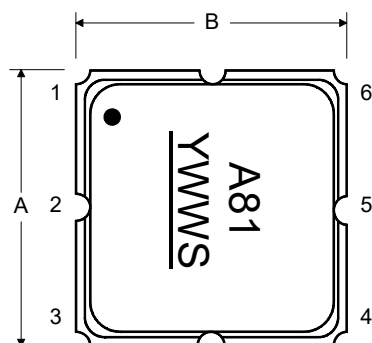
PCB Footprint

Case Dimensions						
Dimension	mm			Inches		
	Min	Nom	Max	Min	Nom	Max
A	3.60	3.80	4.0	0.14	0.15	0.16
B	3.60	3.80	4.0	0.14	0.15	0.16
C	1.30	1.50	1.70	0.05	0.06	0.067
D	0.95	1.10	1.25	0.037	0.043	0.05
E	2.39	2.54	2.69	0.090	0.10	0.110
G	0.90	1.0	1.10	0.035	0.04	0.043
H	1.90	2.0	2.10	0.75	0.08	0.83
I	0.50	0.6	0.70	0.020	0.024	0.028
J	1.70	1.8	1.90	0.067	0.07	0.075

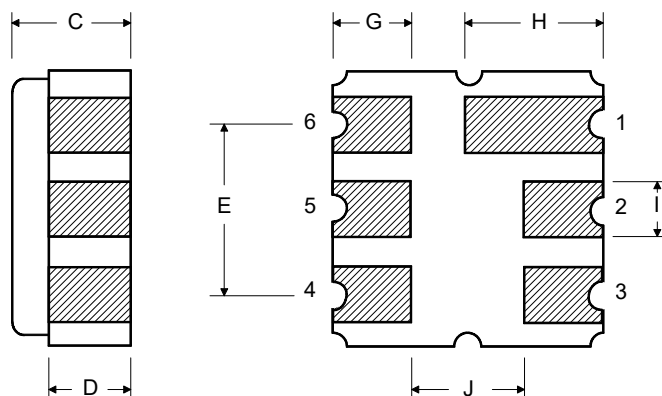
Electrical Connections		
Connection		Terminals
Port 1	Single-ended Input	2
Port 2	Single-ended Output	5
	Ground	All others
Single-ended Operation Only		
Dot indicates Pin 1		

Materials	
Solder Pad Plating	0.3 to 1.0 μ m Gold over 1.27 to 8.89 μ m Nickel
Lid Plating	2.0 to 3.0 μ m Nickel
Body	Al ₂ O ₃ Ceramic

TOP VIEW



BOTTOM VIEW



Recommended Reflow Profile

1. Preheating shall be fixed at 150~180°C for 60~90 seconds.
2. Ascending time to preheating temperature 150°C shall be 30 seconds min.
3. Heating shall be fixed at 220°C for 50~80 seconds and at 260°C +0/-5°C peak (10 seconds).
4. Time: 5 times maximum.

